Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED
LP711 (E) – 60 LEAD 7x11 (QFN) PLASTIC PACKAGE: 77mm²

LP711 (E) PCB Outline Drawing

NOTES:
1. ALL DIMENSIONS ARE IN INCHES [MM]
2. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
3. PAD BURR LENGTH SHALL BE 0.15 mm MAX. PAD BURR HEIGHT SHALL BE 0.05 mm MAX.
4. PACKAGE WARP SHALL NOT EXCEED 0.05 mm
5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND
6. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.
Suggested LP711 (E) PCB Land Pattern

Table 1. Package Information

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking</th>
</tr>
</thead>
<tbody>
<tr>
<td>HMC6001LP711E</td>
<td>RoHS-compliant Low Stress Injection Molded Plastic Silica and Silicon</td>
<td>100% matte Sn</td>
<td>MSL3</td>
<td>H6001 XXXX</td>
</tr>
</tbody>
</table>

[1] 4-Digit lot number XXXX